



Semiconductor Device Type: RTB-VQFN-32-5x5x1mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Lead Frame				28.06	100.00%	41.22%		
	Copper	7440-50-8	27.33		97.43%		40.16%	401626
	Iron	7439-89-6	0.66		2.35%		0.97%	9687
	Lead	7439-92-1	0.00		0.01%		0.00%	41
	Phosphorus	7723-14-0	0.02		0.08%		0.03%	340
	Zinc	7440-66-6	0.04		0.13%		0.05%	515
Die				3.25	100.00%	4.77%		
	Silicon	7440-21-3	3.25		100.00%		4.77%	47737
Die Attach				0.34	100.00%	0.50%		
	Silver	7440-22-4	0.25		73.95%		0.37%	3673
	Carbocyclic Acrylate	Trade Secret	0.07		20.00%		0.10%	993
	Acrylate	Trade Secret	0.02		5.50%		0.03%	273
	2-(3,4-Epoxy)cyclohexyl)ethyltrimethoxysilane	3388-04-3	0.00		0.55%		0.00%	27
Die Pad Plating				0.64	100.00%	0.93%		
	Silver	7440-22-4	0.64		100.00%		0.93%	9345
Bond Wire				0.20	100.00%	0.29%		
	Gold	7440-57-5	0.20		100.00%		0.29%	2865
Mold Compound				34.26	100.00%	50.34%		
	Silica (Fused)	60676-86-0	26.88		78.45%		39.49%	394901
	Epoxy Resin	Trade Secret	2.57		7.50%		3.78%	37753
	Silicon Dioxide	7631-86-9	2.57		7.50%		3.78%	37753
	Metal Hydroxide	Trade Secret	1.03		3.00%		1.51%	15101
	Phenol Resin	Trade Secret	1.03		3.00%		1.51%	15101
	Carbon Black	1333-86-4	0.19		0.55%		0.28%	2769
Lead Plating				1.33	100.00%	1.95%		
	Tin	7440-31-5	1.33		100.00%		1.95%	19498
<b>Totals</b>			<b>68.06</b>	<b>68.06</b>		<b>100.00%</b>	<b>100.00%</b>	<b>1000000</b>

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